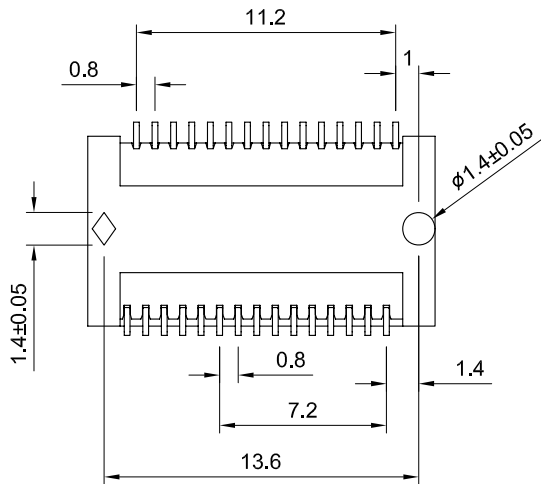
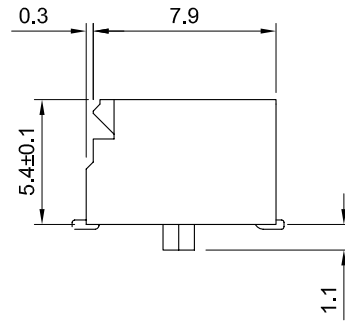
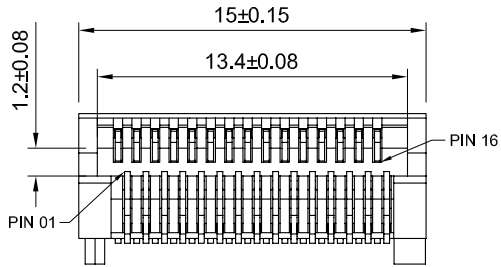
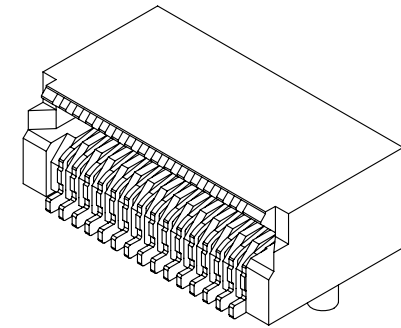
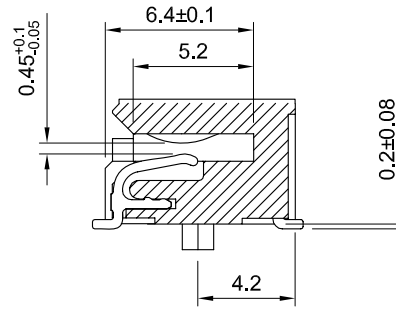
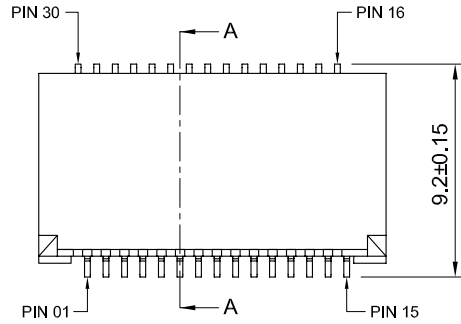


REVISION RECORD				
REV	ECD	DESCRIPTION	DRFT	CHKD



NOTE:
MECHANICAL:

- CONTACT: COPPER ALLOY T=0.20mm.
- HOUSING: THERMOPLASTIC UL 94V-0. COLOR: BLACK.

PLATED:

- CONTACT AREA : PLATING GOLD OVER NICKLE AND 100u"MIN TIN OVER NICKLE

MECHANICAL REQUIREMENT:

- DURABILITY: 250 CYCLES MIN.

ENVIRONMENTAL:

- CONTACT RESISTANCE: 20 MILLIOHMS MAX INITIAL.
- DIELECTRIC WITHSTANDING VOLTAGE: 300V AC/MIN.
- OPERATION TEMPERATURE: -55°C~+85°C.
- STORAGE TEMPERATURE: -55°C~+85°C.
- WAVE SOLDERING TEMPERATURE:255~265°C(5~10SECOND).
- ROHS COMPLIANT

PART NUMBER: XXFP-CONN-01X

01-SERIAL NUMBER GOLD PLATING: 1-3u' 2-6u'
3-15u' 4-30u'
5-50u'

DETACHED LISTS	MM (INCH)		DFTD JACK	DATE 12/01/2011	Xmultiple Technologies, Inc.	
	TOLERANCES EXCEPT AS NOTED		CHKD	DATE		
	MM	±	MFO	DATE	TITLE XFP CONNECTOR	
	.0 ± 0.20	±	APPV: JOHN	DATE 12/01/2011		
.00 ± 0.15	±	MATERIAL :		DRAWING NO. XFPCONN-001		
.000 ± 0.075	±	FINISH:		/PART NO. SEE NOTE		
ANGLES ±		QT'Y :		SIZE	REV	
THIRD ANGLE PROJECTION		SCALE :		A3		
DO NOT SCALE DRAWING				SHEET 1 OF 2		

8

7

6

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2

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A

B

C

D

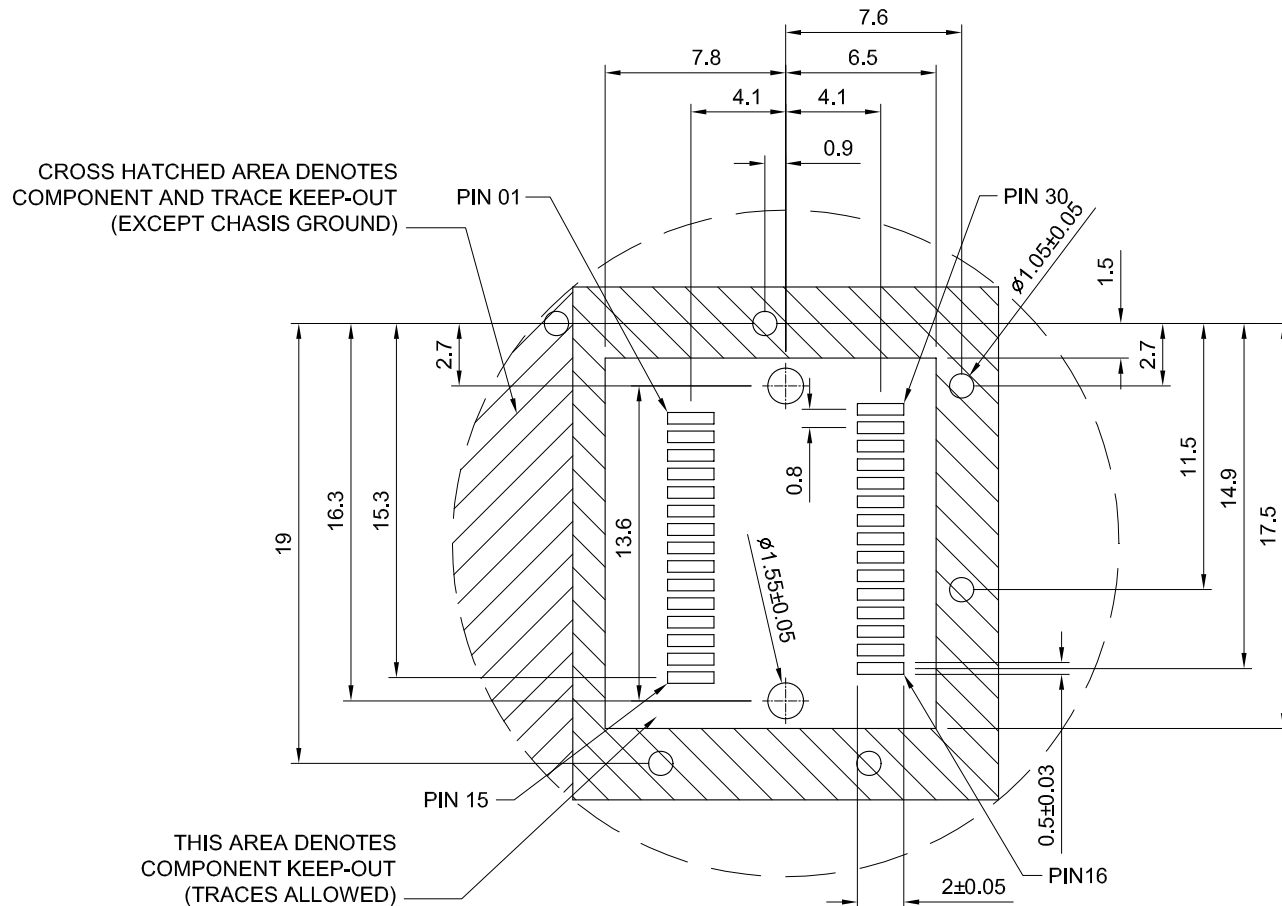
E

F

G

H

REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD



30 CIRCUIT MOTHER BOARD
RECOMMENDED PCB LAYOUT

DETACHED LISTS MH (INCH) TOLERANCES EXCEPT AS NOTED MH ± 0.20 .00 ± 0.15 .000 ± 0.075 ANGLES ± THIRD ANGLE PROJECTION	DFTD JACK DATE 12/01/2011	Xmultiple Technologies, Inc. TITLE XFP CONNECTOR		
	CHKD DATE			
	APPVL JOHN DATE 12/01/2011	MATERIAL :	DRAWING NO. XFPCONN-001 /PART NO. SEE NOTE	SIZE A3
	FINISH:	QT'Y :	DO NOT SCALE DRAWING	REV SHEET 2 OF 2

8

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4

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2

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H
G
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E
D
C
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